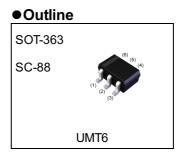


# UMX1N FHA

General purpose transistor (dual transistors)

Parameter	Tr1 and Tr2	
V <sub>CEO</sub>	50V	
۱ <sub>C</sub>	150mA	



# ●Inner circuit

#### 

# Features

- 1) Two 2SC2412K chips in a UMT package.
- 2) Mounting possible with UMT3 automatic mounting machines.
- 3)Transistor elements are independent, eliminating interference.
- 4)Mounting cost and area can be cut in half.

# Application

GENERAL PURPOSE SMALL SIGNAL AMPLIFIER

# Packaging specifications

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
UMX1N FHA	SOT-363 (UMT6)	2021	TN	180	8	3000	X1

# • Absolute maximum ratings ( $T_a = 25^{\circ}C$ ) <It is the same ratings for the Tr1 and Tr2>

Parameter		Symbol	Values	Unit
Collector-base voltage		V <sub>CBO</sub>	60	V
Collector-emitter voltage			50	V
Emitter-base voltage		V <sub>EBO</sub>	7	V
Collector current		Ι <sub>C</sub>	150	mA
Deven die ein etien	total	P <sub>D</sub> <sup>*1</sup>	150	mW
Power dissipation	element	P <sub>D</sub>	120	mW
Junction temperature			150	°C
Range of storage temperature		T <sub>stg</sub>	-55 to +150	°C

# •Electrical characteristics ( $T_a = 25^{\circ}C$ ) <It is the same characteristics for the Tr1 and Tr2>

Deremeter	Current of	Symbol Conditions		Values		Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Collector-base breakdown voltage	BV <sub>CBO</sub>	Ι <sub>C</sub> = 50μΑ	60	-	-	V	
Collector-emitter breakdown voltage	BV <sub>CEO</sub>	I <sub>C</sub> = 1mA	50	-	-	V	
Emitter-base breakdown voltage	BV <sub>EBO</sub>	Ι <sub>Ε</sub> = 50μΑ	7	-	-	V	
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> = 60V	-	-	100	nA	
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> = 7V	-	-	100	nA	
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> = 50mA, I <sub>B</sub> = 5mA	-	-	400	mV	
DC current gain	h <sub>FE</sub>	V <sub>CE</sub> = 6V, I <sub>C</sub> = 1mA	120	-	560	-	
Transition frequency	f <sub>T</sub>	V <sub>CE</sub> = 12V, I <sub>E</sub> = -2mA, f = 100MHz	-	180	-	MHz	
Output capacitance	C <sub>ob</sub>	V <sub>CB</sub> = 12V, I <sub>E</sub> = 0A, f = 1MHz	-	2.0	3.5	pF	

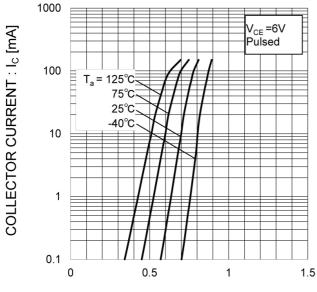
\*1 Each terminal mounted on a reference land.



## •Electrical characteristic curves (T<sub>a</sub> = 25°C)

<For Tr1 and Tr2 in common>

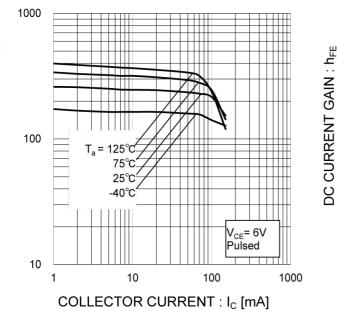




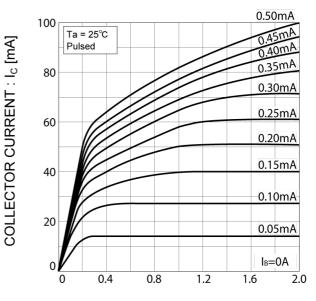
BASE TO EMITTER VOLTAGE : V<sub>BE</sub> [V]

# Fig.3 DC Current Gain vs. Collector Current (I)

DC CURRENT GAIN : hFE

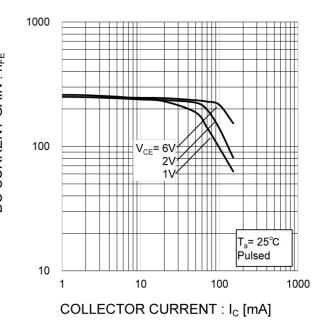


## Fig.2 Grounded Emitter Output Characteristics



COLLECTOR TO EMITTER VOLTAGE :  $V_{CE}$  [V]

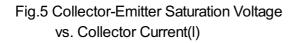
## Fig.4 DC Current Gain vs. Collector Current (II)

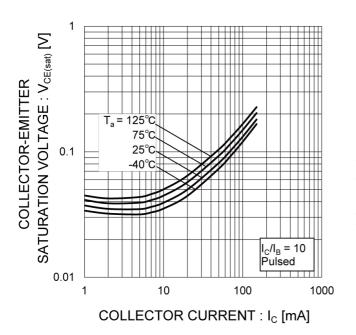




# • Electrical characteristic curves (T<sub>a</sub> = 25°C)

<For Tr1 and Tr2 in common>





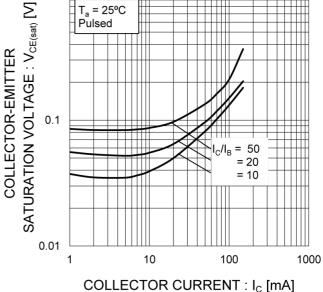


Fig.6 Collector-Emitter Saturation Voltage vs. Collector Current(II)

1

Fig.7 Base-Emitter Saturation Voltage vs. Collector Current (I)

> -40°C 25°C 75°C

125°C

10

100

10

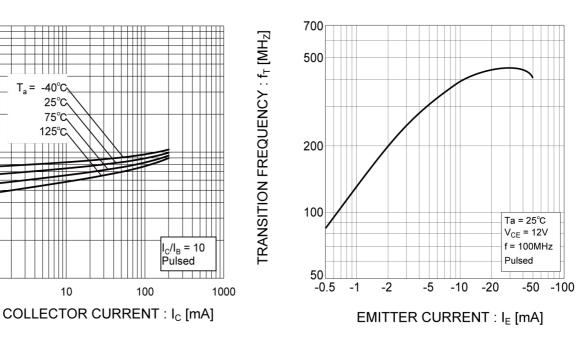
SATURATION VOLTAGE : V<sub>BE(sat)</sub> [V]

0.1

1

**BASE-EMITTER** 

Fig.8 Gain Bandwith Product vs. **Emitter Current** 





# •Electrical characteristic curves (T<sub>a</sub> =25°C)

<For Tr1 and Tr2 in common>

Fig.9 Collector Output Capacitance vs. Collector-Base Voltage Emitter Input Capacitance vs. Emitter-Base Voltage

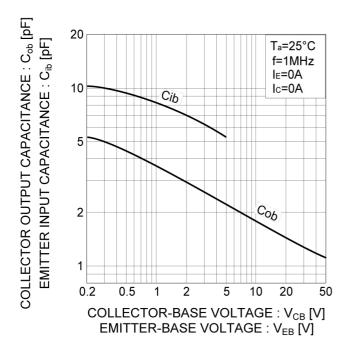
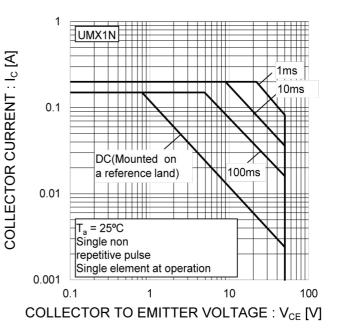


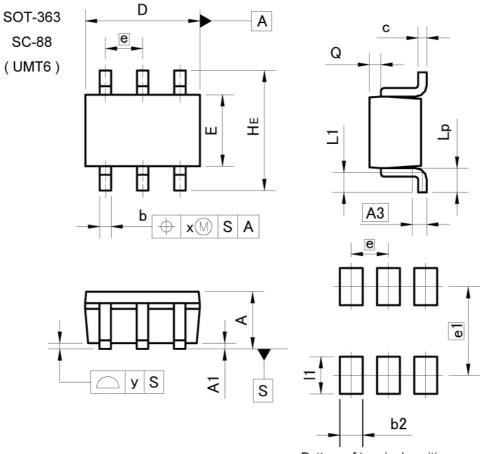
Fig.10 Safe Operating Area





## **UMX1N FHA**

## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	DIM		INC	HES		
DIM	MIN	MAX	MIN	MAX		
A	0.80	1.00	0.031	0.039		
A1	0.00	0.10	0.000	0.004		
A3	0.3	25	0.010			
b	0.15	0.30	0.006	0.012		
с	0.10	0.20	0.004	0.008		
D	1.90	2.10	0.075	0.083		
E	1.15	1.35	0.045	0.053		
е	0.65		0.026			
HE	2.00	2.20	0.079	0.087		
L1	0.10	0.40	0.004	0.016		
Lp	0.25	0.55	0.010	0.022		
Q	0.10	0.30	0.004	0.012		
x	-	0.10	-	0.004		
У	-	0.10	-	0.004		
DIM	MILIMETERS		INCHES			
	MIN	MAX	MIN	MAX		
b2	-	0.40	-	0.016		
e1	1.	1.55		61		
1	-	0.65	-	0.026		

Dimension in mm/inches



# Notice

### Precaution on using ROHM Products

1. If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment <sup>(Note 1)</sup>, aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

JAPAN	USA	EU	CHINA
CLASSI	CLASSⅢ	CLASS II b	CLASSII
CLASSⅣ	CLASSI	CLASSⅢ	CLASSII

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[b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure

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  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

### Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

#### **Precaution for Product Label**

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

#### **Precaution for Disposition**

When disposing Products please dispose them properly using an authorized industry waste company.

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